



MRSI Solutions

For Dispense and Assembly

Volume XVII

Welcome to MRSI Solutions Newsletter. This periodic newsletter provides information on our latest happenings and product updates.

Many thanks to our loyal customers for their continued interest in our products.

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MRSI Provides MRSI-M3 Die Bonding Assembly Work Cell to Fabrinet

MRSI Systems Provides MRSI-M3 Die Bonding Assembly Work Cell to Fabrinet in Silicon Valley for Fast Prototyping and New Product Introduction

MRSI Systems will supply its flagship MRSI-M3 precision die bonding assembly work cell to the Fabrinet West facility in Santa Clara, CA, USA. Advanced optoelectronic and microelectronic component and module products are experiencing record volumes driven by the rapid growth in cloud computing, data transfer and storage, and the adoption of the internet-of-things. This high volume and high growth trend has challenged component and module providers to produce prototypes quickly during product development and subsequently to scale to high volume manufacturing, fast and risk free. To respond to these challenges, Fabrinet is setting up an advanced optical packaging center in its facility in Santa Clara to provide fast prototyping and process development capability for customers of both Fabrinet and MRSI Systems. This application center, equipped with the MRSI-M3 die bonder along with many other capabilities, such as active optical alignment, wire bond, epoxy underfill, laser dicing, and various metrology tools, will further assist our customers in advanced product development and fast ramping to volume manufacturing. Fabrinet and MRSI Systems have agreed to form a partnership to provide the best support to customers on the West Coast, with both easy access to a state-of-the-art packaging facility and the ability to accelerate new product development and risk-free scaling to volume production.

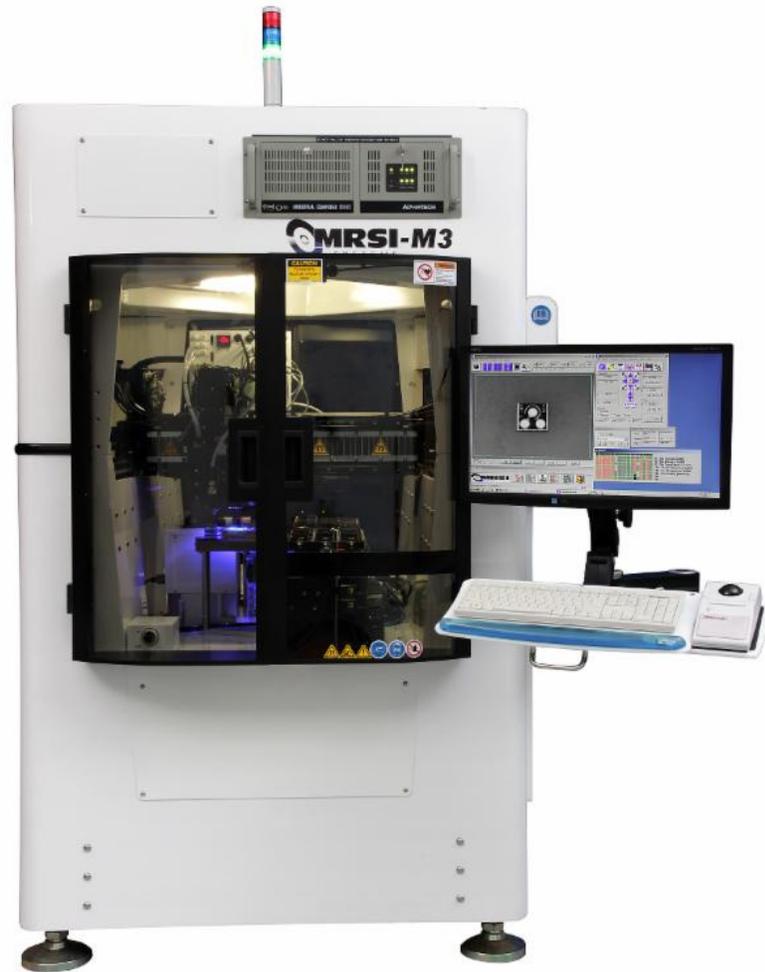
MRSI-M3 delivers an industry-leading combination of accuracy, speed and reliability for complex eutectic bonding with scrubbing and/or force, integrated epoxy dispensing and stamping, thermal and UV epoxy bonding, and flip chip bonding. It provides the best flexibility in the industry handling multiple die sizes and carrier geometries for complex multi-die packaging or fabrication of multiple products. The system's real-time closed-loop force control enables placement of delicate components either mechanically fragile or structurally complex for photonics, RF and microwave, sensor, MEMS and other applications. Die can be picked from waffle pack, Gel-Pak™, wafer, and tape and reel. The MRSI-M3 can be configured for flexible applications during prototyping or more dedicated processes during volume manufacturing.

"MRSI Systems has been serving optoelectronic and microelectronic customers for the past thirty-two years. Fabrinet is the industry leader in contract manufacturing for advanced packaging of complex products and has been a great customer to us.

Both companies also serve the same customer base and market segments," said Mr. Michael Chalsen, President of MRSI Systems. "We are very pleased to partner with Fabrinet in creating an application center in Silicon Valley to help our customers accelerate advanced product development and risk-free scaling to volume manufacturing."

"Fabrinet is very pleased to partner with MRSI Systems to support our shared customer base in our new Fabrinet West facility located at the heart of the Silicon Valley. MRSI Systems is the industry leader in providing equipment and solutions for one of the most critical processes in advanced packaging - ultra-precision and high speed die bonding," said Dr. Hong Hou, Executive Vice President and Chief Technology Officer of Fabrinet. "Fabrinet and its customers have been working with MRSI Systems for many years because of their product's performance, reliability, and field service, particularly their platform design in meeting unique needs from prototyping to high volume manufacturing. We are looking forward to further our collaboration in this application center with their advanced equipment and expertise to serve our customers."

Fabrinet is a leading provider of advanced optical packaging and precision optical, electro-mechanical, and electronic manufacturing services to original equipment manufacturers of complex products, such as optical communication components, modules and subsystems, industrial lasers and sensors. Fabrinet offers a broad range of advanced optical and electro-mechanical capabilities across the entire manufacturing process, including process design and engineering, supply chain management, manufacturing, advanced packaging, integration, final assembly and test. Fabrinet focuses on production of high complexity products in any mix and volume. Fabrinet maintains engineering and manufacturing resources and facilities in Thailand, the United States of America, and the People's Republic of China.



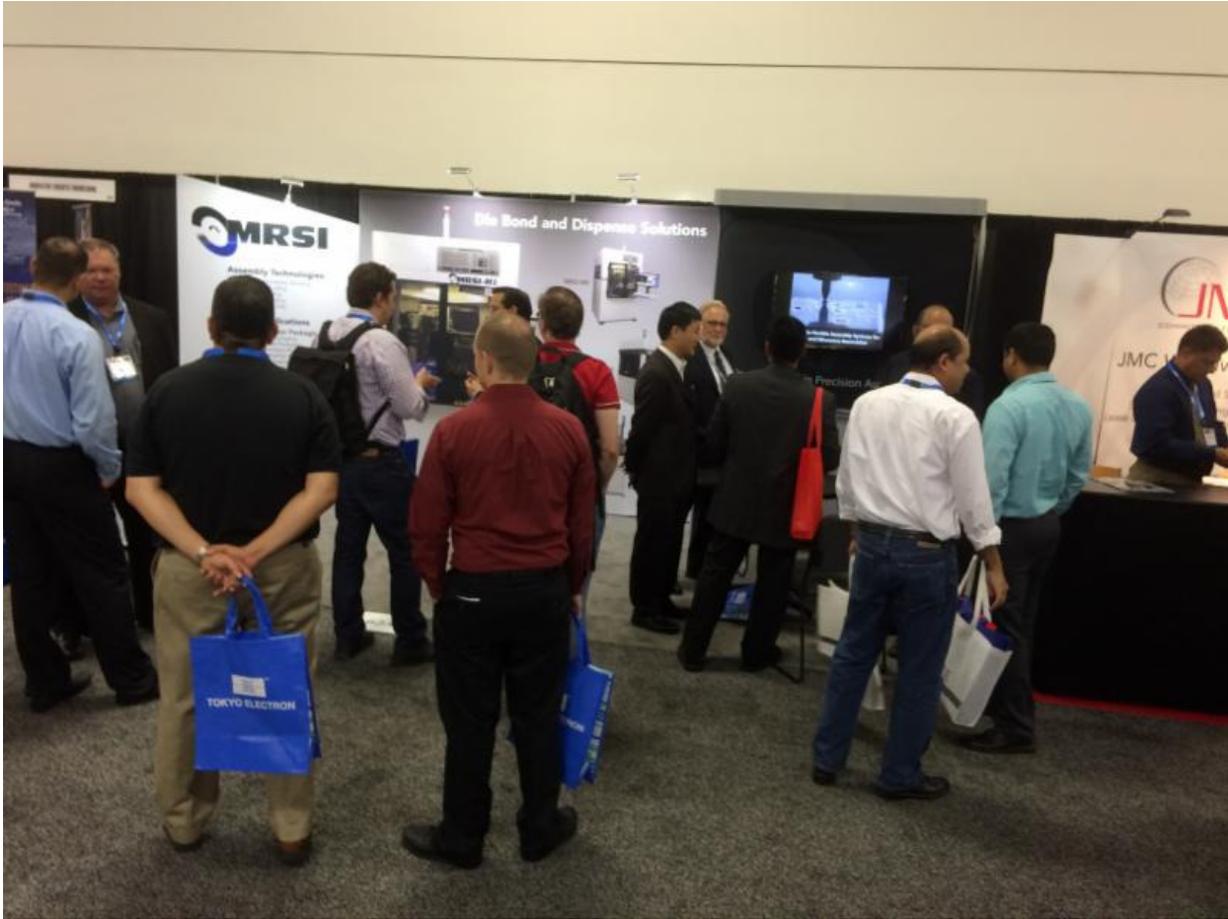
MRSI-M3 Ultra-Precision Die Bonder

Semicon West Trade Show

MRSI will be exhibiting at Semicon West. SEMICON West 2016 will feature 700 exhibitors and more than 115 hours of programs and networking events to connect the supply chain and provide the insights, access, and technical and business intelligence.

We hope to see you there!

- Semicon West will be held at the July 12 - 14, 2016
- Moscone Center
- San Francisco, CA
- MRSI Booth # 122



MRSI - M Series
1-3 Micron Assembly Work Cell



MRSI - 705
5 Micron Assembly Work Cell



MRSI-175Ag
Epoxy Dispenser



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